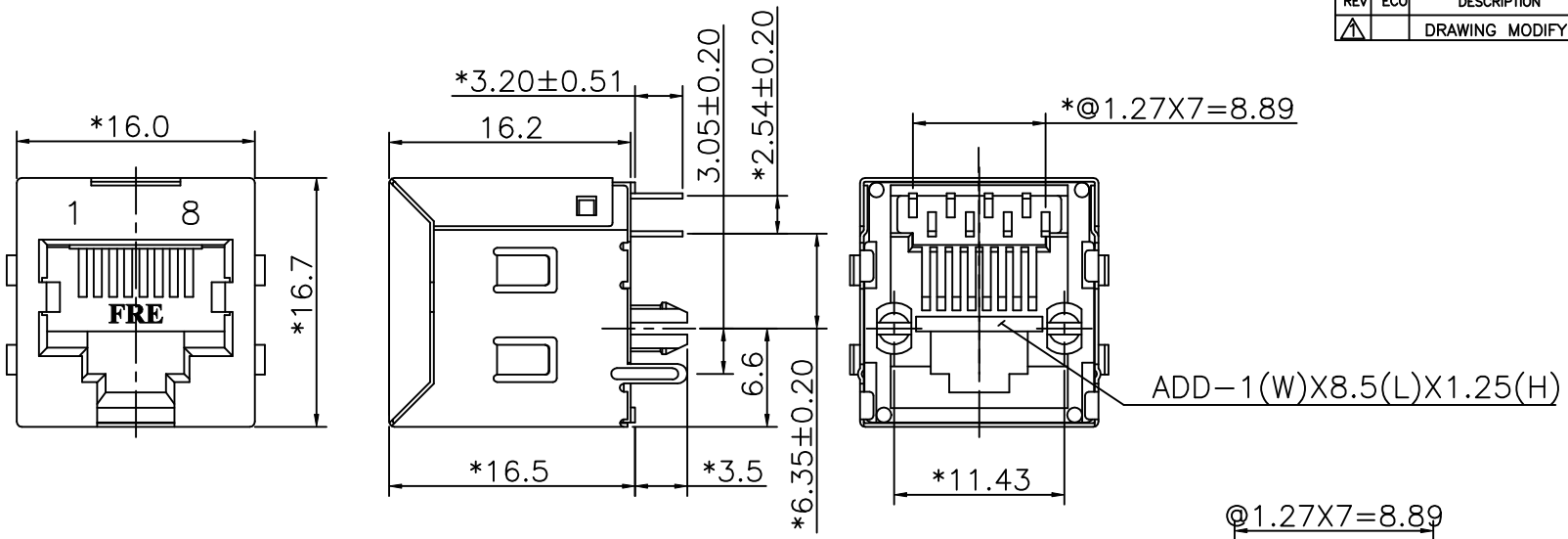
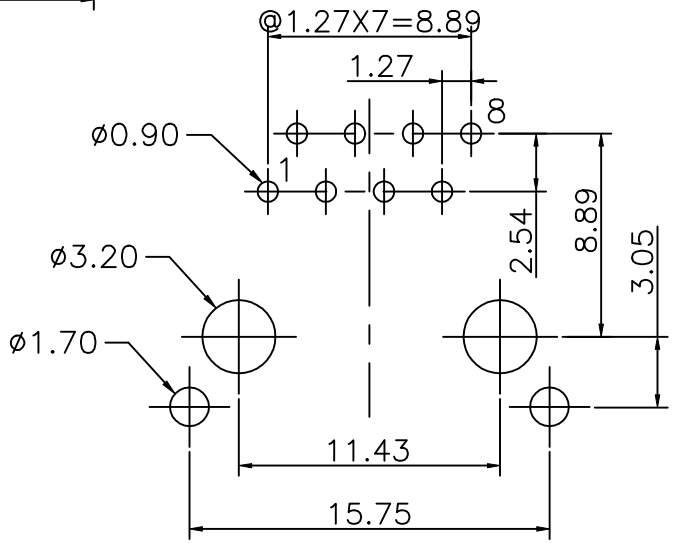
D1RFRD006

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
1		DRAWING MODIFY	JAMYIN 12/13/05	





PC Board Layout Component Side Shown

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : PBT UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
2. OPERATION: 0°C TO 70°C.
3. WAVE SOLDER TEMPERTURE:230~250°C(5~10SECONDS).

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.

CUL FILE NO. E163191

ROHS PART NUMBER: E5288-3X0X4X-L

SHIELD PLATING:
- 1- TIN PLATING,W/ SIDE TABS
- 2- NICKEL PLATING,W/ SIDE TABS
- S- TIN PLATING,W/O SIDE TABS
- T- NICKEL PLATING,W/O SIDE TABS

GOLD PLATING:
- 1- 3u" 2- 6u"
- 3-15u" 4-30u"
- 5-50u"

- 0-PBT+15%G.F (BK)
- 1-PBT+30%G.F (BK)
- L-PBT+30%G.F (YELLOW)

MM (INCH)	DFTO SAMMY	DATE 03/16/05	FULL RISE ELECTRONIC CO., LTD
TOLERANCES EXCEPT AS NOTED	CHKD ANKUE	DATE 2005/12/14	
MM .0 ±0.20 ± .00 ±0.15 ± .000 ±0.075 ±	MFO	DATE	TITLE RJ45 TOP ENTRY PCB MODULAR JACK(DIP TYPE)
	APPVL LUSHENG	DATE 2005/12/14	
	MATERIAL :		
ANGLES ±	QT'Y :		DRAWING NO. GE523014-LC / PART NO. SEE NOTE — SIZE A3 — REV 1
THIRD ANGLE PROJECTION	FINISH :		
	SCALE : 3:1		DO NOT SCALE DRAWING — SHEET X OF Y

DETACHED LISTS